EMPC 2017 - CONFERENCE FRAMEWORK PROGRAM

	Monday, 11th Sept.			Tuesday, 12th Sept.			Wednesday, 13th Sept.	
08:45 – 10:30	PLENARY SESSION 1 – CONFERENCE OPENING + 2 KEYNOTE LECTURES		09:00 – 10:30	PLENARY SESSION 2 (2 KEYNOTE LECTURES)		09:15 – 10:00	PLENARY SESSION 3 (KEYNOE LECTURE)	
10:30 – 11:00	Coffee break		10:30 – 11:00	Coffee break		10:00 – 10:30	Coffee break	
11:00 – 13:00	ORAL SESSION 1 – Advanced packaging and interconnects (6 PRES.)	ORAL SESSION 2 - Printed, hybrid and flexible electronics (6 PRES.)	11:00 – 13:00	ORAL SESSION 7 Materials and processes (6 PRES.)	ORAL SESSION 8 Functional systems (actuators, sensors, photovoltaics and related) (6 PRES.)	10:30 – 12:30	ORAL SESSION 13 - Materials and processes (6 PRES.)	ORAL SESSION 14 – Modeling, design test & reliability (6 PRES.)
13:00 – 14:00	Lunch		13:00 – 14:00	Lunch		12:30 – 13:00	CONFERENCE CLOSING + INFORMATION ABOUT ESTC 2018 and EMPC 2019	
14:00 – 15:40	ORAL SESSION 3 - Materials and processes (5 PRES.)	ORAL SESSION 4 - Functional systems (actuators, sensors, photovoltaics and related) (5 PRES.)	14:00 – 15:40	ORAL SESSION 9 – Advanced packaging and interconnects (5 PRES.)	ORAL SESSION 10 – Modeling, design test & reliability (5 PRES.)	13:00 – 14:00	Lunch	
15:40 – 16:10	Coffee break		15:40 – 16:10	Coffee break				
16:10 – 17:30	ORAL SESSION 5 - Materials and processes (4 PRES.)	ORAL SESSION 6 - Modeling, design test & reliability (4 PRES.)	16:10 – 17:30	ORAL SESSION 11 - Advanced packaging and interconnects (4 PRES.)	ORAL SESSION 12 – Electronics components assembly and PCB solutions (4 PRES.)			
17:30 – 19:00	POSTER SESSION 1 – Advanced packaging and interconnects, Electronics components assembly and PCB solutions, Materials and processes		17:30 – 19:00	POSTER SESSION 2 – Printed, hybrid and flexible electronics, Modeling, design test & reliability, Functional systems (actuators, sensors, photovoltaics and related)				
19:00 – 21:00	WELCOME RECEPTION		19:00 – 22:30	GALA DINNER				

21st European Microelectronics and Packaging Conference, Warsaw, 10-13 SEPTEMBER – detailed preliminary program

MONDAY, 11th SEPTEMBER

PLENARY SESSION 1, Chairs:		
08:45 – 09:00	Conference opening	
09:00 – 09:45	Eric Beyne, IMEC International, Leuven (BELGIUM)	3D System Integration. An Interconnect Hierarchy driven Technology Landscape
09:45 – 10:30	Matti Mäntysalo, Tampere University of Technology (FINLAND)	Printed stretchable electronics – enabler of unobtrusive biosignal monitoring

	ORAL SESSION 1 - Advanced packaging and interconnects (1), Chairs:		ORAL SESSION 2 - Printed, hybrid and flexible electronics, Chairs:	
11:00 – 11:20	Dohle, Rainer; Rittweg, Thomas; Sacco, Ilaria (Micro Systems Engineering GmbH, Berg, GERMANY)	Small Form-Factor, Liquid-Cooled SiPM Module for PET/MRI Applications	Song, Joon Yub; Kim, Yongjin; Lee, Jae Hak; Kim, Seung Man; Lee, Sangil (Korea Inst. of Machinery and Materials, SOUTH KOREA)	Experimental Investigation on 3D Metal Inter-connection for HySiF(hybrid system in flexible) Devices Using ElectroHydroDynamic (EHD) System
11:20 – 11:40	Fujimura, Tsubasa; Inoue, Kotoku; Takayama, Masatoshi; Onitake, Sigeo (Koto Electric Co., Ltd., JAPAN)	Direct copper metallization on TGV Thru-Glass-Via) for high performance glass substrate	Schubert, Martin; Friedrich, Sabine; Bock, Karlheinz (TU Dresden, GERMANY)	3D printed flexible substrate with pneumatic driven electrodes for health monitoring
11:40 – 12:00	Duval, Fabrice F. C.; Wang, Teng; Capuz, Giovanni; Bex, Pieter; Rebibis, Kenneth J.; Lofrano, Melina; Sleeckx, Erik; Beyne, Eric (IMEC, BELGIUM)	Impact of the combination of a stress buffer layer and a wafer level underfill on 3D IC assembly using thermal compression bonding	Alavi, Golzar; Sailer, Holger; Albrecht, Bjoern; Harendt, Christine; N.Burghartz, Joachim (Inst. for Nano and Microelectronic System, GERMANY)	Optimized Adaptive Layout Technique for Hybrid System in Foil
12:00 – 12:20	Kärnfelt, Camilla R. G.; Gallée, François; Castel, Vincent; Sinou, Maïna; Coant, Pascal (Inst. Mines-Telecom/IMT Atlantique, FRANCE)	Experimental LTCC platform for millimeter-wave applications	Lorenz, Lukas; Nieweglowski, Krzysztof; Wolter, Klaus-Jürgen; Hoffmann, Gerd-Albert; Overmeyer, Ludger; Reitberger, Thomas; Franke, Jörg; Bock, Karlheinz (TU Dresden, GERMANY)	Additive waveguide manufacturing for optical bus couplers by aerosol jet printing using conditioned flexible substrates
12:20 – 11:40	Wagner, David; Pitschmann, Kai; Schumann, Ulrich; Freidank, Sebastian; Schmidt, Bertram; Detert, Markus (Otto-von-Guericke Univ. Magdeburg, GERMANY)	Hot bar joining method for medical applications	Gräf, Daniel; Ischdonat, Nils; Hedges, Martin; Franke, Jörg (Friedrich-Alexander-Univ. of Erlangen-Nuremberg, GERMANY)	Data and Power Distribution via Printed Electronics in Aerospace Applications
12:40 – 13:00	Lin, Stanley; Hsu, Ian; Chen, Chi-Yuan; Cho, NamJu; Hsieh, Ming-Che (STATS ChipPAC Pte. Ltd., SINGAPORE)	Fine Pitch High Bandwidth Flip Chip Package-on-Package Development	Krzemiński, Jakub; Kanthamneni, Akhil; Wagner, David; Detert, Markus; Schmidt, Bertram; Jakubowska, Małgorzata (Warsaw Univ. of Techology, POLAND + GERMANY)	Pads and microscale vias with aerosol jet printing technique

	ORAL SESSION 3 - Materials and processes (1), Chairs:		ORAL SESSION 4 - Functional systems (actuators, sensors, photovoltaics and related) (1), Chairs:	
14:00 – 14:20	Reinhardt, Kathrin; Hofmann, Nancy (Fraunhofer IKTS, Dresden, GERMANY)	The importance of shear thinning, thixotropic and viscoelastic properties of thick film pastes to predict effects on printing performance	Nieweglowski, Krzysztof; Lorenz, Lukas; Lüngen, Sebastian; Tiedje, Tobias; Bock, Karlheinz (TU Dresden, GERMANY)	Flexible optical waveguide-based interconnects for electro-optical system integration
14:20 – 14:40	Kärnfelt, Camilla R. G. (Inst. Mines-Telecom/IMT Atlantique, FRANCE)	Passive component development in LTCC	Woźniak, Łukasz Rafał; Kalinowski, Paweł Jan; Jasiński, Grzegorz Paweł; Jasiński, Piotr Zbigniew (Gdansk Univ. of Technology, POLAND)	TEMPERATURE MODULATED SEMICONDUCTOR GAS SENSOR UNDER HUMIDITY INTERFERENCE
14:40 – 15:00	Ivanov, Artem (Univ. of Applied Sciences Landshut, GERMANY)	Evaluation of Piezoelectric Parameters of Several Commercial Thick Film Capacitor Dielectrics	Somer, Jakub; Urban, Frantisek; Szendiuch, Ivan (Brno Univ. of Technology, CZECHIA)	Optical pressure sensors for harsh environment
15:00 – 15:20	Maxa, Jacob; Novikov, Andrej; Nowottnick, Mathias (Rostock Univ., GERMANY)	Thermal Peak Management using Organic Phase Change Materials for Latent Heat Storage in Electronic Applications	Bartoszek, Justyna; Karczewski, Jakub; Mroziński, Aleksander; Wang, Sea-Fue; Jasiński, Piotr (Gdansk Univ. of Technology, POLAND + TAIWAN)	Distribution of relaxation times as a method of separation and identification of complex processes measured by impedance spectroscopy
15:20 – 15:40	Jang, Keon-Soo; Eom, Yong-Sung; Choi, Kwang-Seong; Bae, Hyun-Cheol (ETRI, SOUTH KOREA)	Solvent-free fluxing underfill film for electrical interconnection	Kim, Yeong K.; Shin, Sojin (Inha Univ., SOUTH KOREA)	Signal analyses of airbag sensor by side impact

	ORAL SESSION 5 - Materials and processes (2), Chairs:		ORAL SESSION 6 - Modeling, design test & reliability (1), Chairs:	
16:10 – 16:30	Ziesche, Steffen (Fraunhofer IKTS, GERMANY)	Technological Innovations for the Manufacturing of Multilayer Ceramic Micro-Electro-Mechanical-Systems	Wang, Lei; Xu, Cheng; Cao, Liqiang; Zhang, Wenqi (Fudan Univ., CHINA)	Impact of process induced stresses in flip chip package
16:30 – 16:50	Hanss, Alexander; Elger, Gordon (Technische Hochschule Ingolstadt, GERMANY)	Residual Free Solder Processes for Fluxless Solder Pastes	Boettge, Bianca; Klengel, Sandy (Fraunhofer Inst. for Microstructure of Materials and Systems, GERMANY)	The influence of humidity, temperature and electrical fields on the insulating properties of power electronics housing materials
16:50 – 17:10	Schulz, Alexander; Goudouri, Ourania Menti; Kollenberg, Wolfgang; Müller, Jens (TU Ilmenau, GERMANY)	3D printed ceramic structures based on LTCC: Materials, Processes and Characterizations	Schwarzer, Christian; Fuchs, Dennis; Rauer, Miriam; Lang, Kurt-Juergen; Krügelstein, Andreas; Kaloudis, Michael; Franke, Jörg (Fraunhofer, GERMANY)	Investigation of the Influence of Voids on the Reliability of LED Solder Joints by Computer Tomography and Forward Voltage Measurement
17:10 – 17:30	Löffler, Sebastian; Richter, Nico; Mauermann, Christopher; Rebs, Angela; Reppe, Günter (Cicor - RHe Microsystems GmbH, GERMANY)	Multilayer thick-film ceramic for MCM with Laser Microvias	Bryant, Keith (SMART Group, UNITED KINGDOM)	Advances in X-ray for Semicon Applications

17:30 – 19:00	POSTER SESSION 1, Chairs:
Sakamoto, Mamoru; Nakadozono, Kenichi; Iwanabe, Keiichiro; Asano, Tanemasa (Kyushu Univ., JAPAN)	Time evolution of strain distribution during ultrasonic bonding of Cu wire - Impact of bonding temperature
Gutzeit, Nam; Schulz, Alexander; Welker, Tilo; Wagner, Christoph; Schäfer, Eric; Müller, Jens (TU Ilmenau, GERMANY)	High-precision picosecond laser structuring on LTCC for silicon chip assembly with high electrical contact density
Yu, Ho Chieh {Jay}; Huang, Jason (Sentec E&E Co.,LTD, TAIWAN)	Ceramic in Board (CIB) substrate for high power applications
Sitek, Janusz; Koscielski, Marek; Dawidowicz, Piotr; Ciszewski, Piotr; Khramova, Mariia; Nguyen Quang, Duc; Martinez, Sergio (Tele and Radio Research Inst., POLAND + FINLAND)	Investigations of temperature resistance of memory BGA components during multi-reflow processes for Circular Economy applications
Otáhal, Alexandr; Somer, Jakub; Szendiuch, Ivan (Brno Univ. of Technology, CZECHIA)	Influence of Heating Direction on BGA Solder Balls Structure
Kim, Yongjin; Zaidi, Syed Asad Ali; Lee, Jae Hak; Kim, Seung Man; Song, Joon Yub (Korea Inst. of Machinery and Materials, SOUTH KOREA)	Fabrication of Dry-patching Superhydrophobic Flexible Platform for HySiF (hybrid system in flexible) Applications
EOM, Yong-Sung; JANG, Keon-Soo; SON, Ji-Hye; BAE, Hyun-Cheol; CHOI, Kwang-Seong (ETRI, SOUTH KOREA)	Low-temperature Sintering Behavior of Ternary solder and Copper Powder for High-power Device Packaging
Kruegelstein, Andreas; Franke, Joerg; Goetze, Elisa; Zanger, Frederik; Schulze, Volker; Rohde, Magnus (Friedrich-Alexander-Univ. Erlangen-Nuremberg, GERMANY)	Mechatronic Integrated Devices based on Ceramic Injection Molding for Power Electronics by using Active Solder
Welker, Tilo; Gutzeit, Nam; Müller, Jens (Technische Universität Ilmenau, GERMANY)	Enhanced Heat Spreading in LTCC Packages utilizing Thick Silver Tape in the Co-fire Process
Lahokallio, Sanna; Kiilunen, Janne; Frisk, Laura (Trelic Ltd, FINLAND)	The Transmittance Properties of Optical Adhesives in Humid Environmental Aging
ABDENACER, AIT MANI; BORIS, BOUILLARD; ADRIEN, GASSE; MARION, VOLPERT; BRIGITTE, SOULIER; DAVID, HENRY; AURELIE, VANDENEYNDE; BERTRAND, CHAMBION; PAMELA, RUEDA; FREDERIC (CEA GRENOBLE, FRANCE)	High voltage WireLED powered directly by mains 230 Volts
Daoud, Haneen; Reichelt, Stephan; Loidolt, Angela (Pfarr Stanztechnik GmbH, GERMANY)	Preforms based diffusion soldering process to be used under conventional soldering process conditions
Chew, Ly May; Schmitt, Wolfgang; Nachreiner, Jens; Schnee, Daniel (Heraeus Deutschland GmbH & Co. KG, GERMANY)	Sintered Ag joints on copper lead frame TO220 by pressure sintering process with improved reliability and bonding strength

Tuesday, 12th SEPTEMBER

PLENARY SESSION 2, Chairs:		
09:00 – 09:45	Rao R Tummala, Georgia Institute of Technology (UNITED STATES)	Future of Embedding and Fanout Packaging Technologies
09:45 – 10:30	Krzysztof Koziol, University of Cambridge (UNITED KINGDOM)	Large scale sustainable production of graphene for real-life applications

	ORAL SESSION 7 - Materials and processes (3), Chairs:		ORAL SESSION 8 - Functional systems (actuators, sensors, photovoltaics and related) (2), Chairs:	
11:00 – 11:20	Inoue, Masahiro; Iida, Masaki; Sakaniwa, Yoshiaki (Gunma Univ., JAPAN)	Low temperature sintering of silver micro-particles induced by organic accelerators in epoxy-based binders	Bartsch, Heike; Rydosz, Artur; Maziarz, Wojciech; Pisarkiewicz, Tadeusz; Stöpel, Dirk; Müller, Jens (TU Ilmenau, GERMANY + POLAND)	Printed heater elements for smart sensor packages in LTCC
11:20 – 11:40	Aguilar, Rodrigo (Inventec Performance Chemicals, FRANCE)	Solderability and Reliability Evolution of No-Clean Solder Fluxes	Fischer, Michael; Stubenrauch, Mike; Naber, Ady; Gutzeit, Nam; Klett, Maren; Singh, Sukhdeep; Schober, Andreas; Witte, Hartmut; Müller, Jens (TU Ilmenau, GERMANY)	LTCC-Based Micro Plasma Source for the Selective Treatment of Cell Cultures
11:40 – 12:00	Tsuno, Akira; Sasaki, Koji; Mizumura, Noritsuka (Namics Europ EmbH, GERMANY + JAPAN)	Development of Low-temperature Sintering Nano-silver Die Attach Materials for Bare Cu Application	Ihle, Martin; Ziesche, Steffen; Gierth, Paul; Tuor, Andreas; Tigelaar, Jonathan (Fraunhofer IKTS, GERMANY)	LTCC Technology for Active Eddy Current Turbocharger Speed Sensors
12:00 – 12:20	Cadalen, Eric; Maire, Olivier (MBDA, FRANCE)	Development of selective conformal coating process based on advanced packaging for harsh environments	Girasek, Tomas; Pietrikova, Alena; Welker, Tilo; Muller, Jens (Technical Univ. of Kosice, SLOVAKIA + GERMANY)	Influence of various micro channels integrated in LTCC multilayer module on the thermal resistance
12:20 – 11:40	Skwarek, Agata; Zachariasz, Piotr; Illés, Balázs; Czeppe, Tomasz; Garzeł, Grzegorz; Witek, Krzysztof (Inst. of Electron Technology, POLAND + HUNGARY)	Are tin-rich solder alloys resistant to tin pest?	Belavič, Darko; Bradeško, Andraž; Makarovič, Kostja; Hodnik, Marjan; Uršič, Hana (HIPOT-RR c/o Jožef Stefan Institute, SLOVENIA)	Basic microfluidic elements in the LTCC structures
12:40 – 13:00	Spies, Irina; Schumacher, Axel; Knappmann, Stephan; Rheingans, Bastian; Janczak-Rusch, Jolanta; Jeurgens, Lars P.H. (Hahn-Schickard, Inst. für Mikro- und Informationstechnik, GERMANY + SWITZERLAND)	Acceleration Measurements during Reactive Bonding Processes	Jasiński, Grzegorz; Kalinowski, Paweł; Woźniak, Łukasz; Jasiński, Piotr (Gdańsk Univ. of Technology, POLAND)	Comparison of an electronic nose based on the semiconducting and electrochemical gas sensors performance for an analysis of toxic gas concentration

	ORAL SESSION 9 - Advanced packaging and interconnects (2), Chairs:		ORAL SESSION 10 - Modeling, design test & reliability (2), Chairs:	
14:00 – 14:20	Eto, Motoki; Haibara, Teruo; Oishi, Ryo; Yamada, Takashi; Uno, Tomohiro; Oyamada, Tetsuya (NIPPON MICROMETAL CORPORATION, JAPAN)	Newly Developed High Reliability Palladium Coated Cu Wire for Automotive Application	Bailey, Chris (Univ. of Greenwich, UNITED KINGDOM)	Modelling the 3D-Printing Process for Electronic Packaging
14:20 – 14:40	Panchenko, Iuliana; Kunz, Martin; Lehmann, Lothar; Atanasova, Tanya; Boettcher, Mathias; Wieland, Marcel; Wolf, Juergen M. (Fraunhofer IZM ASSID, GERMANY)	In-line Metrology for Cu Pillar Applications in Interposer based Packages for 2.5D Integration	Klengel, Sandy; Stephan, Tino; Mühs-Portius, Bolko (Fraunhofer IMWS, GERMANY)	A new method for prediction of corrosion processes in Aluminum housing materials for electronic components
14:40 – 15:00	AVRILLIER, Caroline; METZGER, Pascal; MOTTET, Jean-Stéphane; MACHEDA, Joseph (SET, FRANCE)	Flip-chip bonding: how to meet the high accuracy requirements?	BALMONT, Mickaël; BORD-MAJEK, Isabelle; OUSTEN, Yves (IMS Bordeaux, FRANCE)	Comparative FEM thermo-mechanical simulations for built-in reliability: surface mounted technology versus embedded technology for silicon dies
15:00 – 15:20	Essig, Kay Stefan; Chiu, CT; Kuo, Jarris; Chen, Phidia; Yaonnou, Jean-Marc (ASE Group, BELGIUM + TAIWAN)	High Efficient Mid Power Modules by Next Generation Chip Embedding Technology	Dąbrowski, Arkadiusz; Dziedzic, Andrzej; Czarachowicz, Jakub (Wrocław Univ. of Science and Technology, POLAND)	Pulse stability of low ohmic thick film resistors
15:20 – 15:40	Lykova, Maria; Panchenko, Iuliana; Geidel, Marion; Reif, Johanna; Künzelmann, Ulrich; Lang, Klaus-Dieter (TU Dresden, GERMANY)	Characterisation of Cu/Cu bonding using self-assembled monolayer as oxidation inhibitor	Novak, Michael; Grübl, Wolfgang; Schuch, Bernhard; Ossimitz, Peter (Continental, GERMANY)	Reliability of Embedded Wafer Level Ball Grid Arrays in ?

	ORAL SESSION 11 - Advanced packaging and interconnects (3), Chairs:		ORAL SESSION 12 - Electronics components assembly and PCB solutions, Chairs:	
16:10 – 16:30	Frisk, Laura; Lahokallio, Sanna; Kiilunen, Janne (Trelic Ltd, FINLAND)	Comparison of Microvia HDI PCBs with ACF interconnections in accelerated life testing	Silvano de Sousa, Jonathan; Fulmek, Paul; Unger, Michael; Haumer, Paul; Nicolics, Johann (AT&S AG, AUSTRIA)	Embedded mini Heat Pipes as Thermal Solution for PCBs
16:30 – 16:50	Aasmundtveit, Knut E; Eggen, Trym; Nguyen, Hoang-Vu (Univ. College of Southeast Norway, NORWAY)	In–Bi Low-Temperature SLID Bonding for piezoelectric materials	Kandaswamy, Shri Vishnu; Hiegler, Michael; Schmaderer, Michael; Meier, Stephan; Verderio, Marino (Automotive Lighting, GERMANY + ITALY)	Solder joint reliability analysis of a novel solder-pad design for SMT high power LEDs
16:50 – 17:10	Larsson, Andreas; Tollefsen, Torleif A; Løvvik, Ole Martin; Aasmundtveit, Knut E (TECHNI & Univ. College of Southeast Norway, NORWAY)	Liquid Solid Diffusion (LSD) Bonding – A novel joining technology	Kiilunen, Janne Juha Matti; Frisk, Laura (Trelic Ltd, FINLAND)	The Mechanical Strength of Microvias in Reflow Cycling and Environmental Aging
17:10 – 17:30	Deckert, Martin; Lippert, Michael Thomas; Krzemiñski, Jakub; Takagaki, Kentaroh; Ohl, Frank W.; Schmidt, Bertram (Otto von Guericke Univ. Magdeburg, GERMANY + POLAND)	Polyimide Foil Flip-Chip Direct Bonding	Manessis, Dionysios; Pawlikowski, Jakub; Ostmann, Andreas; Schischke, Karsten; Krivec, Thomas; Podhradsky, Gerhard; Ramellow-Schneider, Martin; Lang, K-D. (Fraunhofer IZM Berlin, GERMANY + AUSTRIA)	Embedding technologies for heterogeneous integration of components in PCBs-an innovative modularisation approach with environmental impact

17:30 – 19:00	POSTER SESSION 2, Chairs:
Lee, Jae Hak; Lee, Chung Woo; Kim, Yong Jin; Kim, Seung Man; Song, Jun-Yeob (Korea Inst. of Machinery and Materials, SOUTH KOREA)	Development of PEB Face-Down Interconnection Process for Ultra Thin Flexible Package
Ivanov, Artem; Wurzer, Maximilian (Univ. of Applied Sciences Landshut, GERMANY)	Integration of Screen-Printed Electroluminescent Matrix Displays in Smart Textile Items – Implementation and Evaluation
Chen, Chiung-Hsiung; Lu, Chun-An (ITRI, TAIWAN)	Open resonator technique for measuring thin dielectric Plate and film
Hieber, Hartmann (ICR, GERMANY)	Physical reliability of textile electronics
Heinig, Andy (Fraunhofer IIS/EAS, GERMANY)	High speed interfaces for chip to chip communication on interposer based integration
Suszyński, Zbigniew; Świta, Robert (Koszalin Technical Univ., POLAND)	Image approximation using B-Spline surfaces
Górecki, Krzysztof; Ptak, Przemysław (Gdynia Maritime Univ., POLAND)	Modelling power LEDs in the COB case with thermal phenomena taken into account
Mazloum-Nejadari, Ali; Lederer, Martin; Khatibi, Golta; Nicolics, Johann (TU Wien, AUSTRIA)	Crystal plasticity modeling of the heat affected zone of copper micro-wires
Galbiati, Enrico (SEM Communitation and GESTLABS, ITALY)	Reliability evaluation of solder joints in electronics assemblies
Zuk, Samuel; Pietrikova, Alena; Vehec, Igor (Technical Univ. of Kosice, SLOVAKIA)	Capacitive touch sensor
Belavič, Darko; Vojisavljević, Katarina; Kuščer, Danjela (HIPOT-RR c/o Jožef Stefan Institute, SLOVENIA)	Ceramic packaging of PiezoMEMS devices
Zachariasz, Piotr; Cvejin, Katarina; Szwagierczak, Dorota; Stoch, Agata (Inst. of Electron Technology, POLAND)	Thick film resistive sensors based on Pr0.9Sr0.1CoO3-δ and Sm0.9Sr0.1CoO3-δ cobaltites for carbon monoxide and nitric oxide detection
Kalinowski, Paweł Jan; Woźniak, Łukasz Rafał; Jasiński, Grzegorz Paweł; Jasiński, Piotr Zbigniew (Gdansk Univ. of Technology, POLAND)	TIME WINDOW BASED FEATURES EXTRACTION FROM TEMPERATURE MODULATED GAS SENSORS FOR PREDICTION OF AMMONIA CONCENTRATION
Jasiński, Grzegorz (Gdańsk Univ. of Technology, POLAND)	Influence of operation temperature instability on gas sensor performance

WEDNESDAY, 13th SEPTEMBER

PLENARY SESSION 3, Chairs:		
09:15 – 10:00	Craig Hillman, DFR Solutions (UNITED STATES)	Developing Damage Models for Solder Joints Exposed to Complex Stress States: Influence of Potting, Coating, BGA Mirroring, and Housing on Solder Joint Fatigue

	ORAL SESSION 13 - Materials and processes (4), Chairs:		ORAL SESSION 14 - Modeling, design test & reliability (3), Chairs:	
10:30 – 10:50	Nishikawa, Hiroshi; Liu, Xiangdong (Osaka Univ., JAPAN)	Effect of bonding conditions on shear strength of joints at 200 ℃ using Sn-coated Cu particle	Czerny, Bernhard; Nielsen, Dennis A.; Bonderup Pedersen, Kristian; Luo, Haoze; Khatibi, Golta; Iannuzzo, Francesco; Popok, Vladimir N.; Pedersen, Kield (TU Vienna, AUSTRIA + DENMARK)	A comparative study of heavy Al wire bond degradation subjected to accelerated mechanical, power and thermal cyclic loads
10:50 – 11:10	Khatibi, Golta; Betzwar Kotas, Agnieszka (TU Wien, AUSTRIA)	Mechanical properties and life time of high Pb-containing solder joints	Reuther, Georg M.; Pflügler, Nadine; Udiljak, Dominik; Pufall, Reinhard; Wunderle, Bernhard (Infineon Technologies AG, GERMANY)	A novel experimental approach to calibrating cohesive zone elements for advanced risk analysis of interface delamination in semiconductor packages
11:10 – 11:30	Walker, Jim; Henry, Jim; Graddy, Ed; Adrian, Barbara (Ferro GmbH, GERMANY + USA)	Low Temperature Co-fired Ceramics; Physical and Electrical Properties as a Function of Firing Temperature	Dudek, Rainer (Fraunhofer ENAS, GERMANY)	A Combined Simulation and Optical Measurement Technique for Investigation of System Effects on Components Solder Fatigue
11:30 – 11:50	Gierczak, Mirosław Gracjan; Prażmowska-Czajka, Joanna; Dziedzic, Andrzej (Wrocław Univ. of Science and Technology, POLAND)	Design, fabrication and experimental characterization of mixed thick-/thin film thermoelectric microgenerators based on constantan/silver	Górecki, Paweł; Górecki, Krzysztof (Gdynia Maritime Univ., POLAND)	Influence of thermal phenomena on characteristics of components of the IGBT module
11:50 – 12:10	Schmitt, Wolfgang; Chew, Ly May; Schnee, Daniel (Heraeus Deutschland GmbH & Co. KG, GERMANY)	Silver sinter paste for SIC bonding with improved mechanical properties	Lorenz, Georg; Simon-Najasek, Michél; Lindner, Achim (Fraunhofer IMWS, GERMANY)	The combined effect of mechanical package stress and humidity on chip corrosion probability
12:10 – 12:30	Mikkonen, Riikka Maria (Tampere Univ. of Technology, FINLAND)	Benchmark Study of Screen Printable Silver Inks on a PPE Based Substrate	Walter, Thomas; Khatibi, Golta (TU Vienna, AUSTRIA)	A delamination study on metallization stacks of power semiconductors

12:30 – 13:00	Conference closing; information about ESTC 2018 and EMPC 2019